

客户 Customer: _____

日期 DATE: _____

纳入仕様书 SPECIFICATION

产 品 名 称 PRODUCT NAME: 叠层宽带片式耦合器

Multilayer Broadband Chip Coupler

贵 司 料 号 YOUR PART NO.: _____

敝 司 料 号 OUR PART NO.: MGMC18H0823G24-C59M

版 本 号 VERSION.: V1.0

接受 RECEPTION THE SPECIFICATION HAS BEEN ACCEPTED. 该纳入仕様书已被我司接受 日期: DATE: 公司: COMPANY:		
批准 CFMD	审核 CHKD	接收 RCVD

本纳入仕様书共 6 页

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纳入仕様书改定履历 **MODIFY HISTORY OF SPECIFICATION**

Ver.	DATE	CONTENT	APPROVED
1	2016.02.17	初稿 Constitute	梁启新

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1 适用范围 Scope

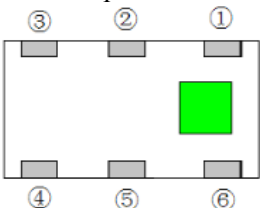
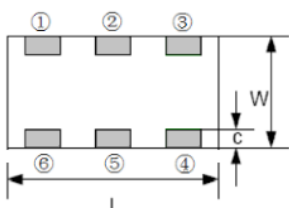
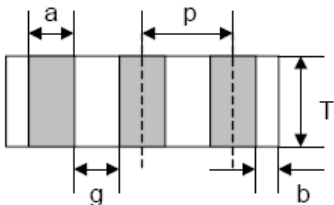
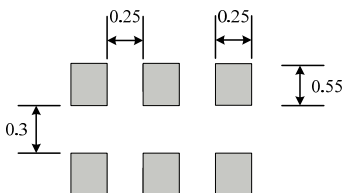
“麦捷”叠层片式耦合器系列产品设计用于 5G、LTE、WIFI、Bluetooth、PDA 和无绳电话机中，具有低的插入损耗、高的隔离度和小体积 SMD 片式设计，能减少复杂的调校工作，可以简化电路设计。

“Microgate” Multilayer chip coupler series are designed to be used in 5G、LTE、WIFI、Bluetooth、PDA & cordless phones with low insertion loss and high isolation as well as small size SMD chip design , which can simplify your complex tuning and circuit design .

2 品名构成 Product Identification

MGMC	18	H	0823G	24	-C59M	
						标准规格，编号/Normal Type: C59M
						耦合度/Coupling: 24.0dB
						频率/Frequency: 0.8GHz/2.3GHz
						设计结构/Design series: H: via design series 过孔设计系列
						产品尺寸/Chip Size: 1.6mm×0.8mm
						叠层宽带片式耦合器/Multilayer Chip Coupler

3 形状、尺寸 Appearance and Dimensions

Unit:mm								
Top View 				Bottom View 				
Side View 				Land Pattern 				
Terminal Configuration								
①	IN			④	Termination			
②	GND			⑤	GND			
③	Main Out			⑥	Coupled Out			
Mark	W	L	T	a	b	c	g	p
Dimensions(mm)	0.8 ± 0.1	1.6 ± 0.1	0.6 ± 0.1	0.2 ± 0.1	0.2 ± 0.1	0.15 ± 0.1	0.3 ± 0.1	0.5 ± 0.1

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4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (-40 to +85℃)

湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85℃

保存温度范围 Storage Temperature Range : -40 to +85℃

No	Item	Specifications	
1	Frequency Range (MHz)	f1	698~960MHz
		f2	1710~2170MHz
		f3	2300~2690MHz
2	Insertion Loss(dB)	f1	0.23max.
		f2	0.25 max..
		f3	0.28 max..
3	Coupling Value(dB)	23.0~27.0dB@698~915MHz	
		21.5~26.5dB@1710~2025MHz	
		22.5~27.5dB@2300~2620MHz	
4	Directivity (dB)	f1	20 min.
		f2	20 min.
		f3	15 min.
5	V.S.W.R	1.45 max.	
6	Characteristics Impedance	50 ohm (Nominal)	
7	Power Capacity	2W max.(50 ohm Load)	

6 焊接条件 Recommended Soldering Conditions

1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

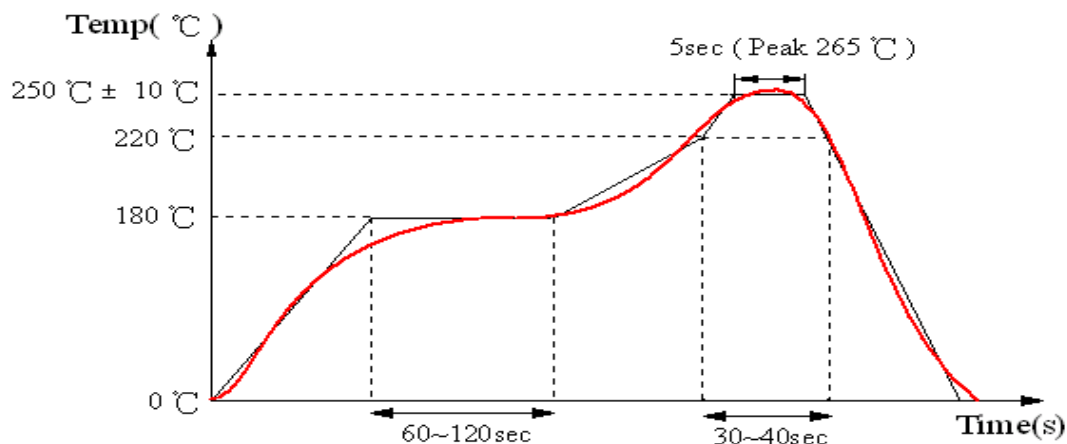
② 使用纯锡焊料 Use Sn solder.

2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150℃, 1 minute
尖端温度 Tip temperature	350℃ max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max